

5      **PROCESSING OF CIRCUIT BOARDS WITH PROTECTIVE, ADHESIVE-  
LESS COVERS ON AREA ARRAY BONDING SITES**

**Abstract of the Disclosure**

10      An apparatus, program product and method for processing circuit boards  
containing area array surface treated bonding sites, such as noble metal terminal pads  
of a Land Grid Array (LGA) assembly. The circuit board includes a plurality of  
apertures patterned about the bonding site for form a footprint. A protective cover  
shaped to conform to the footprint includes posts registered to removably fit into the  
apertures. The protective cover remains overlaid on the circuit board during  
15      fabrication processes such as solder screen printing, rework, and washing, and then  
removed. Thus, contamination from the fabrication processes is avoided, as well as  
eliminating possible sources of contamination from use of adhesive tape for  
protection.